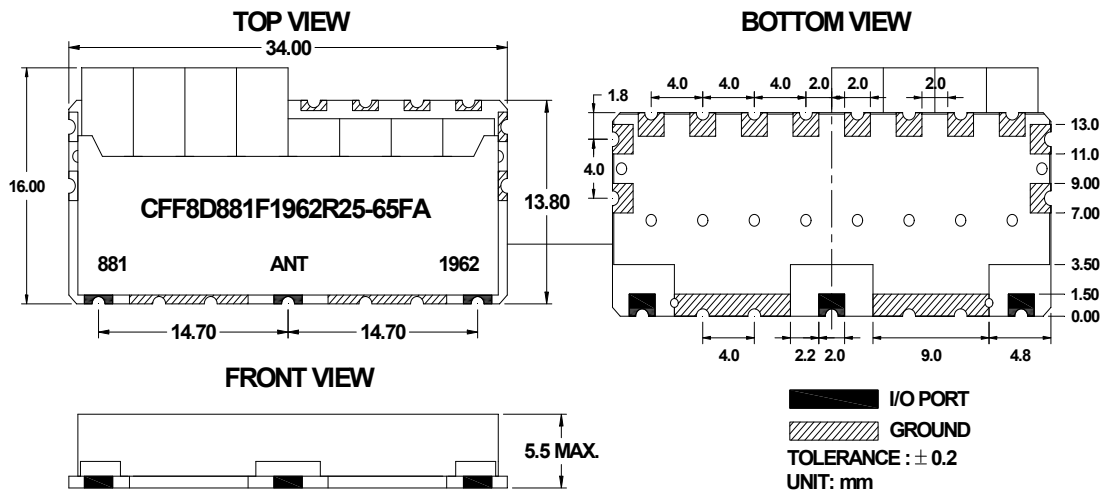


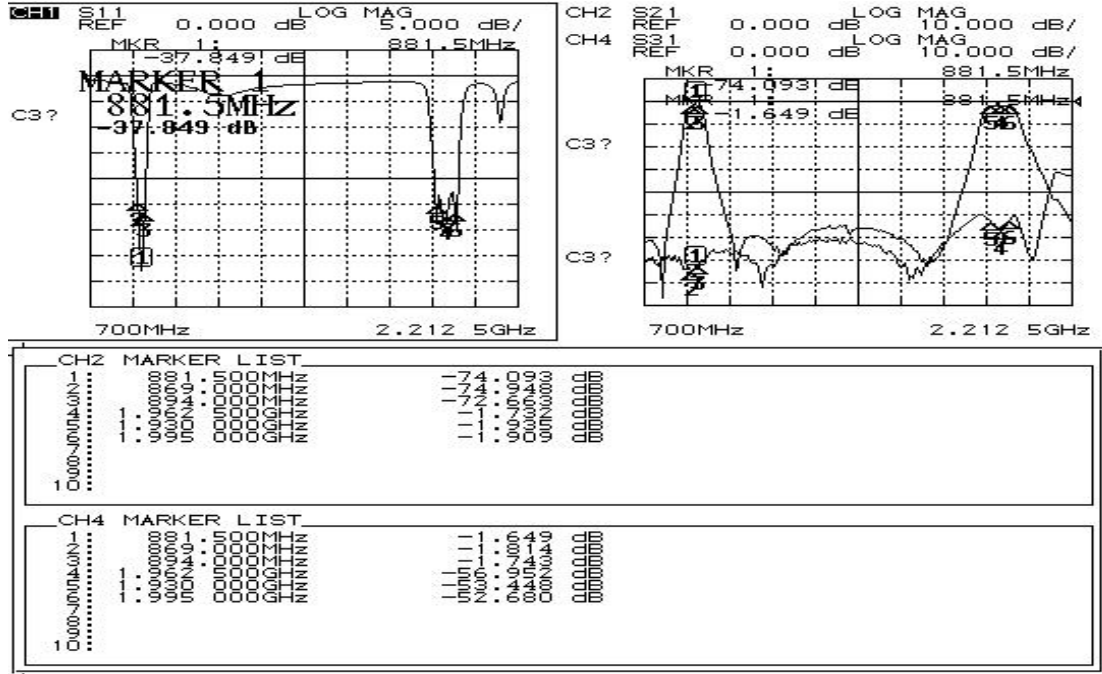
Electrical Specification

ITEMS	ANT>>LOW	ANT>>High	UNIT
Center Frequency [fo]	881.5	1962.5	MHz
Bandwidth [BW]	fo ±12.5 [869 ~ 894]	fo ±32.5 [1930~1995]	MHz
Insertion Loss in BW	2.5	2.5	dB max
Ripple in BW	0.5	0.5	dB max
Return Loss in BW <input type="checkbox"/> ANT Port			dB min
VSW Rin BW <input checked="" type="checkbox"/> ALL Port	1.5	1.5	max
Attenuation <input checked="" type="checkbox"/> Absolute Value <input type="checkbox"/> Relative Value	45dB min @ fo ± [1930 ~1995]	45dB min @ fo ± [869 ~894]	MHz
	dB min @ fo ± [~]	dB min @ fo ± [~]	MHz
	dB min @ fo ± [~]	dB min @ fo ± [~]	MHz
	dB min @ fo ± [~]	dB min @ fo ± [~]	MHz
Isolations	dB min@[~]		MHz
	dB min@[~]		MHz
Input Power	3		W max.
In/Out Impedance	50 Ω		
Operation Temperature Range	-40°C to +85°C		

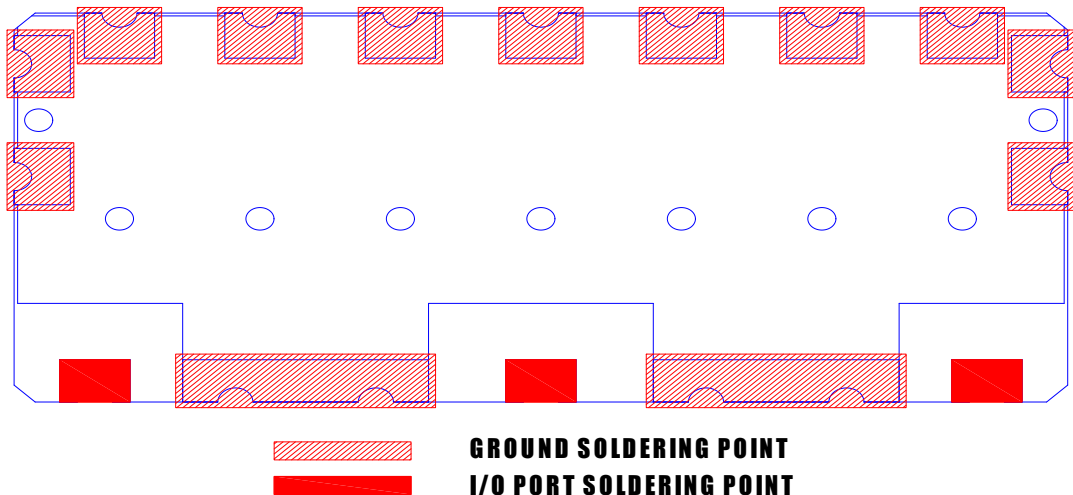
Mechanical Specification



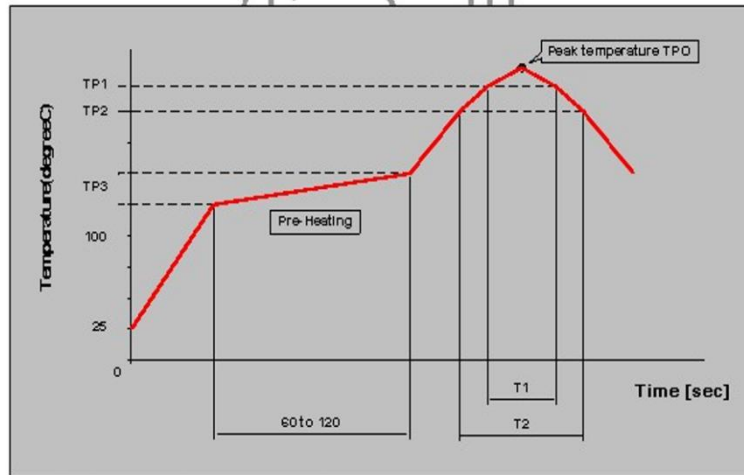
Plot Data



Recommended PC Board Pattern



 Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245±5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260±5/0	240	20	220	70	150 to 180